

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3110	pad near3 reinforc\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:28
L2	327889	"257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:28
L3	199	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:32
L4	4	(("6858944") or ("6825541")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:42
L5	8	(("5965903") or ("6232662") or ("3808474") or ("6551916")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:47
L6	2	("6399897").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:51
L7	2	("6890828").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:51
L8	9	(("5828121" "6057224" "6071805" "6204165" "6211561" "6268261" "6413827" "6555467" "6713835").PN. OR ("6890828").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:51
L9	16	("5530290" "5798559" "6017814" "6057224" "6060381").PN. OR ("6204165").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:52

L10	18	("4899439" "4920639" "5126192" "5171713" "5256274" "5386142" "5567982" "5798559" "5828121" "6016000" "6033996" "6091149" "6184121" "6204165" "6255712").PN. OR ("6596624").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:59
L11	2	("6822329").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:09
L12	2047	(257/784).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:09
L13	2714800	reinforc\$5 or anchor or crackstop or (crack near3 stop) or strength\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:10
L14	5010720	pad or land or contact	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:10
L15	59594	13 near6 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:03
L16	59388	15 not (3 4 5 6 7 8 9 10 11)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:59
L17	13261	(257/784,773,779,786,781,698,758 or 438/612).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:12

L18	551	16 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:15
L19	6	("6297563") or ("5739587") or ("6265313").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:33
L20	2	("6476491").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:33
L21	10	("20010036716" "20020163083" "6084304" "6274935" "6303505" "6376353" "6424036" "6451681" "6468906" "6569767").PN. OR ("6747355").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:37
L22	22	("5502337" "5622590" "5641996" "5700735" "5736791" "5739587" "5939790" "5948533" "5986343" "6020220" "6078088" "6100589" "6108210" "6198170" "6207550" "6218736" "6232650" "6238599" "6239386" "6313540" "6362531" "6365970").PN. OR ("6740985").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:38
L23	28	("5229642" "5751065" "5847466").PN. OR ("6100589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:40
L24	10	("4060828" "6027999").PN. OR ("6306749").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:50
L25	13	("5383093" "5554940" "5686759" "5726458" "5734187" "5760429" "5760477").PN. OR ("5917197").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:53
L26	58830	15 not (3 4 5 6 7 8 9 10 11 18 19 20 21 22 23 24 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04
L27	32204	13 near3 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04

L28	31634	27 not (3 4 5 6 7 8 9 10 11 18 19 20 21 22 23 24 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04
L29	1579	28 and ("438"/\$ or "257"/\$).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:42

Inventor Name Search Result

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Day : Sunday
 Date: 9/18/2005
 Time: 20:31:45

Inventor Name Search Result

Your Search was:

Last Name = YAO

First Name = CHIH-HSIANG

Application#	Patent#	Status	Date Filed	Title	Inventor Name
10269219	6759342	150	10/11/2002	METHOD OF AVOIDING DIELECTRIC ARCING	YAO, CHIH-HSIANG
10322412	6787484	150	12/17/2002	METHOD OF REDUCING VISIBLE LIGHT INDUCED ARCING IN A SEMICONDUCTOR WAFER MANUFACTURING PROCESS	YAO, CHIH-HSIANG
10322691	6812069	150	12/17/2002	METHOD FOR IMPROVING SEMICONDUCTOR PROCESS WAFER CMP UNIFORMITY WHILE AVOIDING FRACTURE	YAO, CHIH-HSIANG
10448656	6831365	150	05/30/2003	METHOD AND PATTERN FOR REDUCING INTERCONNECT FAILURES	YAO, CHIH-HSIANG
10455849	Not Issued	41	06/06/2003	Structure for reducing stress-induced voiding in an interconnect of integrated circuits	YAO, CHIH-HSIANG
10602147	6864701	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF EFFECTIVE VACANCY DIFFUSION AREA	YAO, CHIH-HSIANG
10602751	Not Issued	161	06/24/2003	Hybrid copper/low k dielectric interconnect integration method and device	YAO, CHIH-HSIANG
10602970	6787803	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF LOW-K DIELECTRIC CRACKING THRESHOLDS	YAO, CHIH-HSIANG
10706156	Not Issued	61	11/12/2003	Integration film scheme for copper / low-k interconnect	YAO, CHIH-HSIANG
10716682	6927498	150	11/19/2003	BOND PAD FOR FLIP CHIP PACKAGE	YAO, CHIH-HSIANG
10731983	Not Issued	71	12/10/2003	Structure and method for reinforcing a bond pad on a chip	YAO, CHIH-HSIANG
10742240	Not Issued	71	12/18/2003	Chip orientation and attachment method	YAO, CHIH-HSIANG
10761004	Not	41	01/20/2004	Semiconductor chip singulation method	YAO, CHIH-HSIANG

	Issued				
10780512	Not Issued	60	02/17/2004	Non-repeated and non-uniform width seal ring structure	YAO, CHIH-HSIANG
10908142	Not Issued	30	04/28/2005	Multiple Etch-Stop Layer Deposition Scheme and Materials	YAO, CHIH-HSIANG
10940504	Not Issued	30	09/13/2004	Seal ring structure for integrated circuit chips	YAO, CHIH-HSIANG
10979408	Not Issued	30	11/02/2004	Bond pad structure with stress-buffering layer capping interconnection metal layer	YAO, CHIH-HSIANG
11018604	Not Issued	30	12/21/2004	Test patterns for measurement of effective vacancy diffusion area	YAO, CHIH-HSIANG
11196184	Not Issued	30	08/03/2005	Methods for enhancing die saw and packaging reliability	YAO, CHIH-HSIANG
60477713	Not Issued	159	06/11/2003	Hybrid copper/ low k dielectric interconnect integration method and device	YAO, CHIH-HSIANG

Inventor Search Completed: No Records to Display.

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Day : Sunday
 Date: 9/18/2005
 Time: 20:45:46

Inventor Name Search Result

Your Search was:

Last Name = HUANG

First Name = TAI-CHUN

Application#	Patent#	Status	Date Filed	Title	Inventor Name
09292742	6211574	150	04/16/1999	SEMICONDUCTOR PACKAGE WITH WIRE PROTECTION AND METHOD THEREFOR	HUANG, TAI-CHUN
09323904	6229702	150	06/02/1999	BALL GRID ARRAY SEMICONDUCTOR PACKAGE HAVING IMPROVED HEAT DISSIPATION EFFICIENCY, OVERALL ELECTRICAL PERFORMANCE AND ENHANCED BONDING CAPABILITY	HUANG, TAI-CHUN
09366637	6369439	150	08/04/1999	STRIP OF SEMICONDUCTOR PACKAGE	HUANG, TAI-CHUN
10267769	6825541	150	10/09/2002	BUMP PAD DESIGN FOR FLIP CHIP BUMPING	HUANG, TAI-CHUN
10284715	6858944	150	10/31/2002	BONDING PAD METAL LAYER GEOMETRY DESIGN	HUANG, TAI-CHUN
10353554	Not Issued	41	01/29/2003	Bonding pad and via structure design	HUANG, TAI-CHUN
10448656	6831365	150	05/30/2003	METHOD AND PATTERN FOR REDUCING INTERCONNECT FAILURES	HUANG, TAI-CHUN
10602147	6864701	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF EFFECTIVE VACANCY DIFFUSION AREA	HUANG, TAI-CHUN
10602751	Not Issued	161	06/24/2003	Hybrid copper/low k dielectric interconnect integration method and device	HUANG, TAI-CHUN
10602970	6787803	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF LOW-K DIELECTRIC CRACKING THRESHOLDS	HUANG, TAI-CHUN
10706156	Not Issued	61	11/12/2003	Integration film scheme for copper / low-k interconnect	HUANG, TAI-CHUN
10716682	6927498	150	11/19/2003	BOND PAD FOR FLIP CHIP PACKAGE	HUANG, TAI-CHUN
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10908142	Not Issued	30	04/28/2005	Multiple Etch-Stop Layer Deposition Scheme and Materials	HUANG, TAI-CHUN
10940504	Not Issued	30	09/13/2004	Seal ring structure for integrated circuit chips	HUANG, TAI-CHUN
10979408	Not Issued	30	11/02/2004	Bond pad structure with stress-buffering layer capping interconnection metal layer	HUANG, TAI-CHUN
11018604	Not Issued	30	12/21/2004	Test patterns for measurement of effective vacancy diffusion area	HUANG, TAI-CHUN
11196184	Not Issued	30	08/03/2005	Methods for enhancing die saw and packaging reliability	HUANG, TAI-CHUN
60477713	Not Issued	159	06/11/2003	Hybrid copper/ low k dielectric interconnect integration method and device	HUANG, TAI-CHUN

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